is mounted to the mounting surface. Additionally or alternatively, the cable assembly is sufficiently light to be supportable indefinitely solely by the camera head when the cable assembly is dangling from the camera head. Optionally, and depending on the weight of the processing module, the connection between one or both of i) the cable and the camera head and ii) the cable and the processing module may be reinforced such that the camera head is able to support the cable assembly.

[0013] The image processing circuitry may comprise a processor laid out on the image processing PCB and the processing module may further comprise a heat spreader attached to the processor.

[0014] According to another aspect, there is provided a method for mounting a security camera comprising a camera head and a cable assembly. The method comprises drilling an aperture in a mounting surface, wherein the aperture is sized to allow the cable assembly to pass through it and to be coverable by the camera head when the camera head is secured to the mounting surface; connecting the camera to a network via the cable assembly; inserting the cable assembly through the aperture, and securing the camera head to the mounting surface such that the camera head covers the aperture. The camera head comprises an image sensor and the cable assembly comprises a cable connected to the camera head and a processing module connected to the camera head via the cable. The processing module comprises image processing circuitry communicative with the image sensor and power circuitry electrically coupled to the image processing circuitry and the camera head.

[0015] The cable assembly may be sufficiently light to be supportable indefinitely solely by the camera head when the cable assembly is dangling from the camera head.

[0016] The image processing circuitry may comprise an image processing printed circuit board (PCB); and the power circuitry may comprises a power PCB and wherein both of the PCBs are housed within the processing module.

[0017] The PCBs may be opposite each other. Additionally or alternatively, they may be parallel to each other. Additionally or alternatively, they may have identical dimensions.

[0018] The processing module may further comprise a heat spreader attached to the image processing circuitry.

wherein the image processing PCB and power PCB are positioned parallel to and opposite each other, the processing module is sized to fit through an aperture in a mounting surface that can be covered by the camera head when the camera head is mounted to the mounting surface.

13. The camera of claim 12 wherein the image processing circuitry comprises a processor laid out on the image processing PCB and wherein the processing module further comprises a heat spreader attached to the processor.

14. A method for mounting a security camera comprising a camera head and a cable assembly, the method comprising:

(a) drilling an aperture in a mounting surface, wherein the aperture is sized to allow the cable assembly to pass through it and to be coverable by the camera head when the camera head is secured to the mounting surface;

(b) connecting the camera to a network via the cable assembly, wherein the camera head comprises an image sensor and the cable assembly comprises:

(i) a cable connected to the camera head; and

(ii) a processing module connected to the camera head via the cable, the processing module comprising:

(1) image processing circuitry communicative with the image sensor; and

(2) power circuitry electrically coupled to the image processing circuitry and the camera head;

(c) inserting the cable assembly through the aperture; and

(d) securing the camera head to the mounting surface such that the camera head covers the aperture.

15. The method of claim 14 wherein the cable assembly is sufficiently light to be supportable solely by the camera head when the cable assembly is dangling from the camera head.

16. The method of claims 14 or 15 wherein:

(a) the image processing circuitry comprises an image processing printed circuit board (PCB); and

(b) the power circuitry comprises a power PCB and wherein both of the PCBs are housed within the processing module.

17. The method of claim 16 wherein the PCBs are opposite and parallel to each other.

18. The method of claims 16 or 17 wherein the processing module further comprises a heat spreader attached to the image processing circuitry.

19. The method of claim 18 wherein the image processing circuitry comprises a processor and the heat spreader is attached to the processor.

20. The method of any one of claims 14 to 19 wherein the cable comprises a jacketed micro-coaxial cable having multiple conductors.